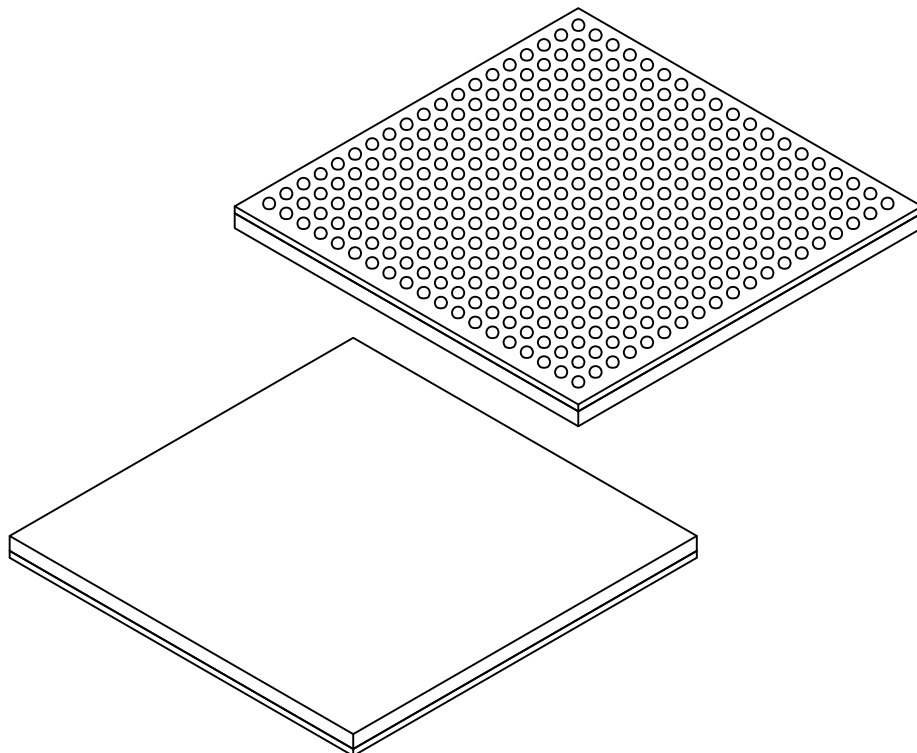


361-Ball Thin Fine Pitch Ball Grid Array (DYB) - 16x16 mm Body [TFBGA] Atmel Legacy Global Package Code CEP

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	361		
Pitch	e	0.80 BSC		
Overall Height	A	-	-	1.20
Standoff	A1	0.27	-	0.37
Overall Length	D	16.00 BSC		
Overall Pitch	D1	14.40 BSC		
Overall Width	E	16.00 BSC		
Overall Pitch	E1	14.40 BSC		
Terminal Width	b	0.38	-	0.48

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.